

#### **DESCRIPTION**

The IS181 series of optocoupler consists of an infrared light emitting diode optically coupled to an NPN silicon photo transistor in a space efficient Mini Flat Package.

#### **FEATURES**

- Low Profile Package
- AC Isolation Voltage 3750V<sub>RMS</sub>
- CTR Selections Available
- Wide Operating Temperature Range -55°C to +110°C
- Lead Free and RoHS Compliant
- UL File E91231 model "FPT1" and "FPT2"

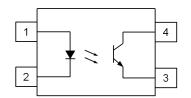
#### **APPLICATIONS**

- Computer Terminals
- Industrial System Controllers
- Measuring Instruments
- Signal Transmission between Systems of Different Potentials and Impedance

### **ORDER INFORMATION**

 Available in Tape and Reel with 3000 pieces per reel





- Anode
- 2 Cathode
- 3 Emitter
- 4 Collector

#### ABSOLUTE MAXIMUM RATINGS $(T_A = 25^{\circ}C)$

Stresses exceeding the absolute maximum ratings can cause permanent damage to the device.

Exposure to absolute maximum ratings for long periods of time can adversely affect reliability.

#### Input

Forward Current	50mA
Reverse Voltage	6V
Power dissipation	70mW

#### **Output**

Collector to Emitter Voltage BV <sub>CEO</sub>	80V
Emitter to Collector Voltage $BV_{\text{ECO}}$	6V
Collector Current	50mA
Power Dissipation	150mW

### **Total Package**

Isolation Voltage	$3750V_{RMS}$
Total Power Dissipation	170mW
Operating Temperature	-55 to 110 °C
Storage Temperature	-55 to 150 °C
Lead Soldering Temperature (10s)	260°C

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# ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = 25°C unless otherwise specified)

# **INPUT**

Parameter	Symbol Test Condition		Min	Тур.	Max	Unit
Forward Voltage	$V_{\mathrm{F}}$	$I_F = 20 \text{mA}$		1.2	1.4	V
Reverse Current	$I_R$	$V_R = 4V$			10	μΑ
Terminal Capacitance	$C_{t}$	V = 0V, $f = 1KHz$		30	250	pF

### **OUTPUT**

Parameter	Symbol	Test Condition	Min	Тур.	Max	Unit
Collector-Emitter Breakdown Voltage	$\mathrm{BV}_{\mathrm{CEO}}$	$I_C = 0.1 \text{mA}, I_F = 0 \text{ mA}$	80			V
Emitter-Collector Breakdown Voltage	$\mathrm{BV}_{\mathrm{ECO}}$	$I_E = 10\mu A, I_F = 0mA$	6			V
Collector-Emitter Dark Current	$I_{CEO}$	$V_{CE} = 20V$ , $I_F = 0mA$			100	nA

# **COUPLED**

Parameter	Symbol	Test Condition	Min	Тур.	Max	Unit
Current Transfer Ratio	CTR	$I_F = 5 \text{mA}, V_{CE} = 5 \text{V}$	50		600	%
		Optional CTR Grades IS181A IS181B IS181C IS181D IS181GR IS181GB	80 130 200 300 100 100		160 260 400 600 300 600	
Collector-Emitter Saturation Voltage	V <sub>CE(sat)</sub>	$I_F = 20 \text{mA}, I_C = 1 \text{mA}$			0.2	V
Floating Capacitance	$C_{\mathrm{f}}$	V = 0V, $f = 1MHz$		0.6	1	pF
Output Rise Time	t <sub>r</sub>	$V_{CE} = 2V$ , $Ic = 2mA$ , $R_{L} = 100\Omega$		4	18	μs
Output Fall Time	$t_{\mathrm{f}}$	$V_{CE} = 2V$ , $Ic = 2mA$ , $R_L = 100\Omega$		3	18	μs

### **ISOLATION**

Parameter	Symbol Test Condition		Min	Тур.	Max	Unit
Insulation Voltage	$V_{\rm ISO}$	RH = 40% to 60%, $t = 1$ min,	3750			V
Input - Output Resistance	R <sub>I-O</sub>	$V_{I-O} = 500 VDC$	5x10 <sup>10</sup>			Ω



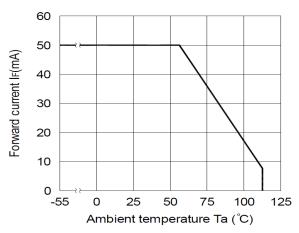


Fig 1 Forward Current vs TA

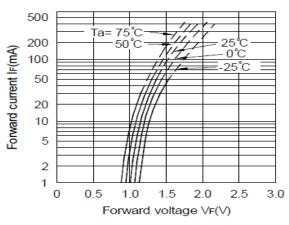


Fig 3 Forward Current vs Forward Voltage

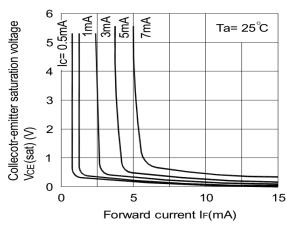


Fig 5 Collector-Emitter Saturation Voltage vs Forward Current

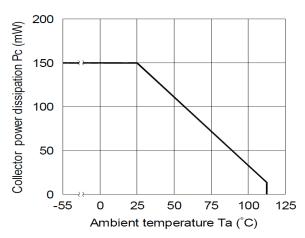


Fig 2 Collector Power Dissipation vs TA

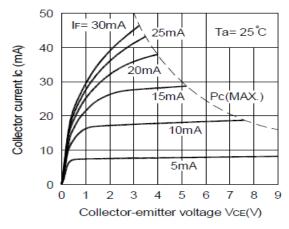


Fig 4 Collector Current vs Collector-Emitter Voltage

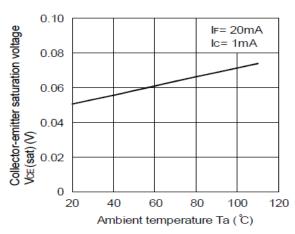


Fig 6 Collector-Emitter Saturation Voltage vs T<sub>A</sub>



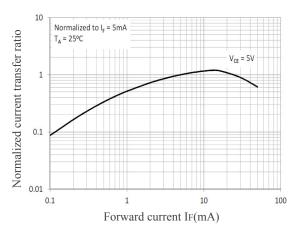


Fig 7 Normalized Current Transfer Ratio vs Forward Current

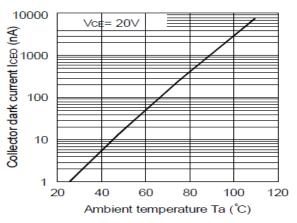


Fig 9 Collector Dark Current vs  $T_A$ 

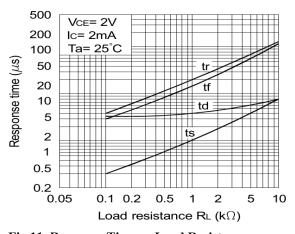


Fig 11 Response Time vs Load Resistance

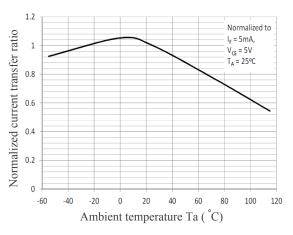


Fig 8 Normalized Current Transfer Ratio vs  $T_{\rm A}$ 

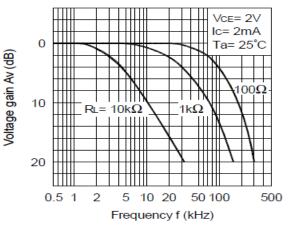
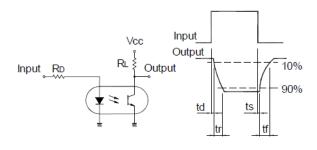


Fig 10 Frequency response



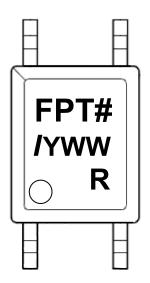


#### **ORDER INFORMATION**

IS181					
After PN	PN	Description	Packing quantity		
None	IS181	Surface Mount Tape & Reel	3000 pcs per reel		
Any CTR Grade	IS181A, IS181B, IS181C, IS181D, IS181GR, IS181GB	Surface Mount Tape & Reel	3000 pcs per reel		

NOTE: Multiple Grades may be supplied to meet the requested specification.

### **DEVICE MARKING**



FPT# denotes Device Part Number where "#" is internal control number

which can be "1" or '2"

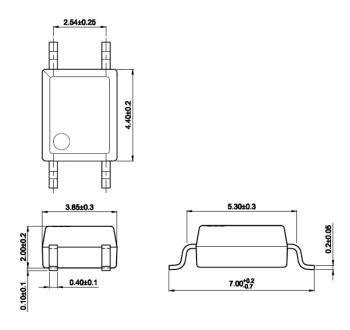
I denotes Isocom

Y denotes 1 digit Year code WW denotes 2 digit Week code

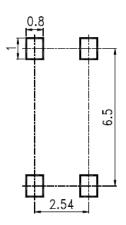
R denotes CTR Grade



# **PACKAGE DIMENSIONS (mm)**

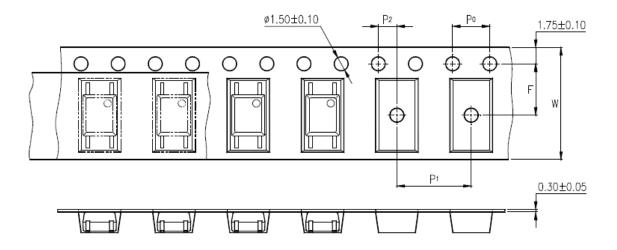


# **RECOMMENDED SOLDER PAD LAYOUT (mm)**





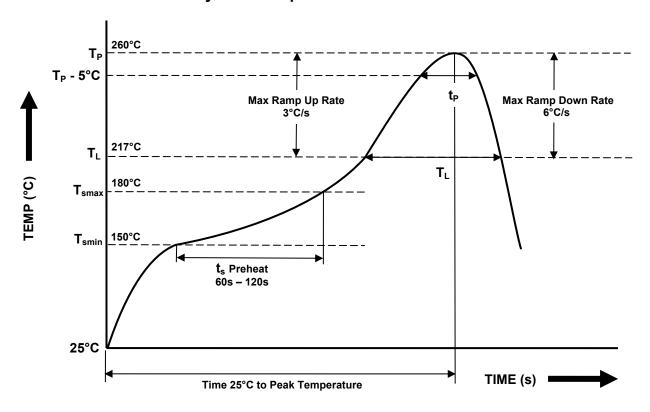
### **TAPE AND REEL PACKAGING**



Description	Symbol	Dimension mm (inch)
Tape Width	W	12 ± 0.3 (0.47)
Pitch of Sprocket Holes	P <sub>0</sub>	4 ± 0.1 (0.15)
Distance of Compartment to Sprocket Holes	F	5.5 ± 0.1 (0.217)
Distance of Compartment to Sprocket Holes	P <sub>2</sub>	2 ± 0.1 (0.079)
Distance of Compartment to Compartment	P <sub>1</sub>	8 ± 0.1 (0.315)



# IR REFLOW SOLDERING TEMPERATURE PROFILE One Time Reflow Soldering is Recommended. Do not immerse device body in solder paste.



Profile Details	Conditions
Preheat - Min Temperature (T <sub>SMIN</sub> ) - Max Temperature (T <sub>SMAX</sub> ) - Time T <sub>SMIN</sub> to T <sub>SMAX</sub> (t <sub>s</sub> )	150°C 180°C 60s - 120s
$\begin{tabular}{lll} \textbf{Soldering Zone} \\ - & \mbox{Peak Temperature } (T_P) \\ - & \mbox{Liquidous Temperature } (T_L) \\ - & \mbox{Time within } 5^{\circ}\mbox{C of Actual Peak Temperature } (T_P - 5^{\circ}\mbox{C}) \\ - & \mbox{Time maintained above } T_L \ (t_L) \\ - & \mbox{Ramp Up Rate } (T_L \ to \ T_P) \\ - & \mbox{Ramp Down Rate } (T_P \ to \ T_L) \\ \end{tabular}$	260°C 217°C 20s 60s 3°C/s max 3 - 6°C/s
Average Ramp Up Rate (T <sub>smax</sub> to T <sub>P</sub> )	3°C/s max
Time 25°C to Peak Temperature	8 minutes max



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